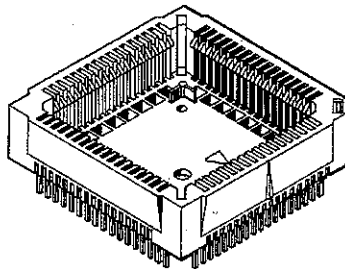
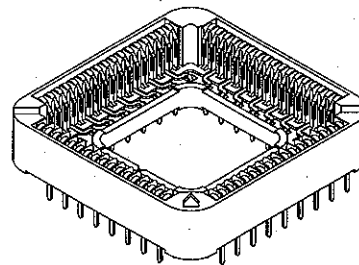


Cross Reference — HPT to PLCC

Plastic Leaded Chip Carrier Sockets



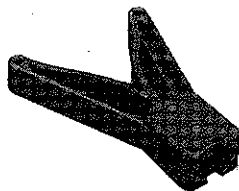
HPT



PLCC

No. of Pos.	Description	HPT Solder Tail Part Number	Equivalent PLCC Solder Tail Part Number
28	Metal Standoffs	821581-1	822437-1
28	Plastic Standoffs	821702-1	822437-1
32	Metal Standoffs	821665-1	822437-2
32	Plastic Standoffs	821684-1	822437-2
44	Metal Standoffs	821575-1	822437-3
44	Plastic Standoffs	821688-1	822437-3
52	Metal Standoffs	821551-1	822437-4
52	Plastic Standoffs	821739-1	822437-4
68	Metal Standoffs	821574-1	822437-5
68	Plastic Standoffs	821689-1	822437-5
84	Metal Standoffs	821573-1	822437-6
84	Plastic Standoffs	821690-1	822437-6

Plastic Leaded Chip Carrier Extraction Tools



No. of Pos.	HPT Solder Tail Part Number	Equivalent PLCC Solder Tail Part Number
28	822045-1	822045-1
32	821980-1	821980-1
44	821981-1	821981-1
52	822049-1	822049-1
68	822026-1	822026-1
84	822268-1	822268-1



All Purpose Extraction
(Not for use with HPT Sockets)
Tool Part No. 822154-1

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Features and Benefits

Feature	Benefit
• Positive contact design • High normal force contacts — above 200 grams • Low profile socket height of .276" off pc board • Uniform solder tail heights with chamfered post tips • Rigid Solder Tails • Single-piece housing • PCT housing material • Visual aids for registration • Open bottom in center of housing • Plastic housing standoffs • Housing slots • Top loaded contacts • Closed bottom housing design on socket periphery • Accepts JEDEC plastic chip carriers made to MS-016 (rectangular packages) and MS-018 (square packages) • Heat age tested to 105°C for 1000 hours	• Prevents package "popout" • Design provides optimum mating and retention of plastic leaded chip carrier and maintains reliable interconnection during life of the sockets • Allows tighter board spacing and clearance between boards • Permits easier insertion into printed circuit board • Protects against damage in handling and insertion into printed circuit board • Prevents flux and solvent entrapment • Allows wave solder or infrared processing • Easy orientation of plastic leaded chip carrier • Allows inspection or repair of components beneath socket • Provides clearance for heat dissipation and cleaning operations • Provides easy access for standard plastic leaded chip carrier extraction tools and all purpose extraxtion tool — AMP Part No. 822154-1 • Eliminates the potential of solder bridging • Eliminates the potential of solder wicking in processing • Permits product standardization • Proves long term reliability of contact design